

What is claimed is:

1. A method of wetting a semiconductor wafer, said method comprising: using a wafer carrier to hold the wafer to a polishing pad; dispensing a chemical through at least one outlet to the polishing pad; and moving the at least one outlet while dispensing the chemical.

5  
2. A method as recited in claim 1, wherein the step of dispensing a chemical comprises dispensing a slurry.

10  
3. A method as recited in claim 1, wherein the step of moving the at least one outlet comprises moving the outlet in an arc motion.

4. A method as recited in claim 1, wherein the step of moving the at least one outlet comprises moving the outlet in a back and forth motion.

15  
5. A method as recited in claim 1, wherein the polishing pad is disposed on a polishing table and said method further comprises rotating at least one of the wafer carrier and the polishing table.

20  
6. A method as recited in claim 1, wherein the step of dispensing a chemical through at least one outlet comprises dispensing a chemical through a plurality of outlets to the polishing pad; and moving the outlets while dispensing the chemical.

7. A method as recited in claim 1, further comprising providing at least one moveable arm which carries said at least one outlet.

5           8. A method as recited in claim 7, further comprising moving said at least one moveable arm while dispensing the chemical.

10          9. A method as recited in claim 8, further comprising moving the at least one moveable arm in an arc motion.

15          10. A method as recited in claim 8, further comprising moving the at least one moveable arm in a back and forth motion.

11. A machine for polishing a semiconductor wafer, said machine comprising: a polishing pad; a wafer carrier configured to hold the semiconductor wafer to the polishing pad; and at least one moveable outlet configured to dispense a chemical to the polishing pad.

20          12. A machine as recited in claim 11, wherein the moveable outlet is configured to move in an arc motion.

13. A machine as recited in claim 11, wherein the moveable outlet is configured to move in a back and forth motion.

14. A machine as recited in claim 11, wherein the polishing pad is disposed on a polishing table and at least one of the wafer carrier and the polishing table is rotatable.

5 15. A machine as recited in claim 11, wherein the at least one moveable outlet comprises a plurality of outlets.

10 16. A machine as recited in claim 11, further comprising at least one moveable arm which carries said at least one outlet.

17. A machine as recited in claim 16, wherein the at least one moveable arm is configured to move in an arc motion.

15 18. A machine as recited in claim 16, wherein the at least one moveable arm is configured to move in a back and forth motion.